

Features

- All diffused structure.
- High current density.
- Very low forward voltage drop.
- Ceramic housing hermetic package.
- Ultra-low thermal resistance

Electrical Characteristics And Ratings

Reverse Blocking:

Device Type	V_{RRM} (1)	V_{RSM} (1)
ZW10500-02	200	300
ZW10500-04	400	450

V_{RRM} = Repetitive peak reverse voltage

V_{RSM} = Non repetitive peak reverse voltage (2)

Repetitive peak reverse leakage current	I_{RRM}	5 mA 75 mA (3)
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Notes:

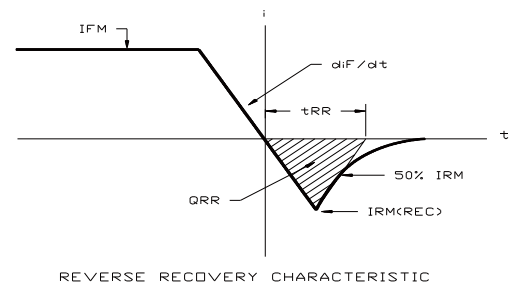
All ratings are specified for $T_j = 25^\circ\text{C}$, unless otherwise stated.

(1) Sine half wave, $f=50\text{Hz}$, $T_j = -40$ to $+180^\circ\text{C}$.

(2) Sine half wave, Pulse width 10 msec. $T_j = -40$ to $+180^\circ\text{C}$.

(3) Maximum value for $T_j = 180^\circ\text{C}$.

(4) See parameter definition below :



Conducting - on state

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Average forward current	$I_{F(AV)}$		10500		A	Sinewave 180°, $T_c = 85^\circ\text{C}$
RMS forward current	I_{FRMS}		16485		A	
Peak one cycle surge (non repetitive) current	I_{FSM}		70000		A	Pulse width 10 msec, sinusoidal wave-shape, 180° conduction, $T_j = 170^\circ\text{C}$
$I^2 t$	$I^2 t$		24000		KA^2s	Pulse width 10 msec, sinusoidal wave-shape, $T_j = 180^\circ\text{C}$
Peak forward voltage	V_{FM}		1.05		V	$I_{FM} = 5000\text{A}$; 25°C
Threshold voltage	V_{TO}		0.8		V	$T_j = 180^\circ\text{C}$
Slope resistance	r_T		0.026		$\text{m}\Omega$	$T_j = 180^\circ\text{C}$
Reverse Recovery Current (4)	$I_{RM(REC)}$				A	$I_{FM} = 1000\text{A}$; $dI_F/dt = 10\text{A}/\mu\text{s}$; T_{jmax}
Reverse Recovery Charge (4)	Q_{rr}				μC	$I_{FM} = 1000\text{A}$; $dI_F/dt = 10\text{A}/\mu\text{s}$; T_{jmax}
Reverse Recovery Time (4)	t_{rr}				μs	$I_{FM} = 1000\text{A}$; $dI_F/dt = 10\text{A}/\mu\text{s}$; T_{jmax}

* For guaranteed maximum values, contact factory

Thermal And Mechanical Characteristics

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Operating temperature	T _j	-40	+180		°C	
Storage temperature	T _{stg}	-40	+180		°C	
Thermal resistance- junction to case	R _{θ(j-c)}		0.005		°C/W	Double sided cooled
Thermal resistance- case to heatsink	R _{θ(j-c)}		0.0025		°C/W	Double sided cooled
Creepage distance	D _s		2		mm	
Air breakdown distance	D _a		2		mm	
Mounting force	F	30	35	32	kN	
Weight	W			460	g	

* Mounting surfaces smooth, flat and greaseless

Case Outline And Dimensions

